



ESD SMD Comm X7R, Ceramic, 0.01 uF, 5%, 16 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 0805, 0.7 mm



General Information		
Series	ESD SMD Comm X7R	
Style	SMD Chip	
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II	
Features	Temperature Stable, Class II	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	11 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	0.78mm +/-0.10mm
S	0.7mm MIN
В	0.5mm +/-0.25mm

Т	0.78mm +/-0.10mm	
S	0.7mm MIN	
В	0.5mm +/-0.25mm	
Packaging Specifications		

Specifications		
Capacitance	0.01 uF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	5%	
Voltage DC	16 VDC	
ESD Level per AEC-Q200	25,000 V ESD Level	
Dielectric Withstanding Voltage	40 VDC	
Temperature Range	-55/+125°C	
Temp. Coefficient	X7R	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms	
Dissipation Factor	3.5% 1 kHz 1.0Vrms	
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

Packaging Specifications		Temp. Coefficient	X7R
Packaging	Bulk, Bag	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Packaging Quantity 1	1		
	Dissipation Factor	3.5% 1 kHz 1.0Vrms	
		Aging Rate	3% Loss/Decade Hour: Refere

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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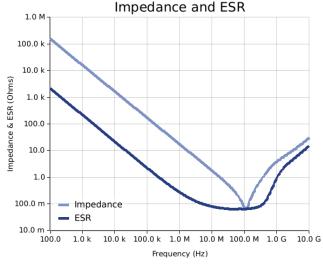


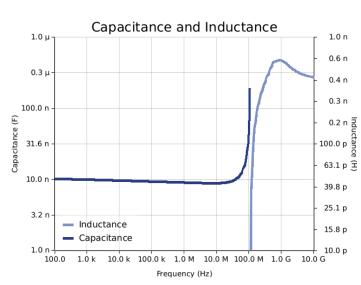


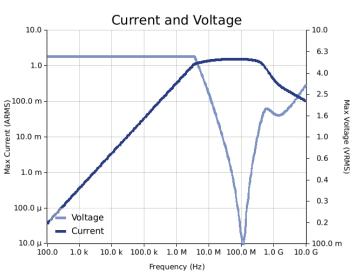
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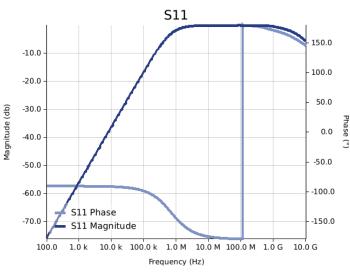
## **Simulations**

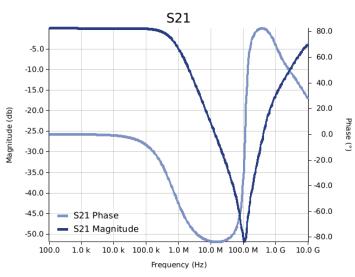
For the complete simulation environment please visit Y-SIM.

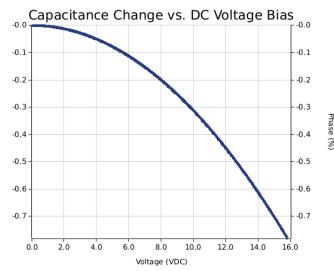












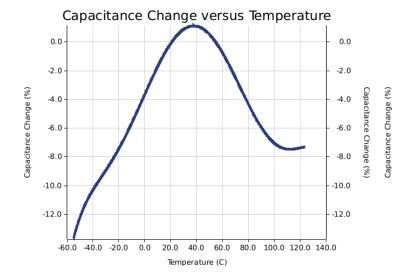
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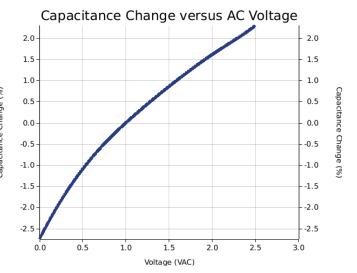
Phase (%)





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## These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR in the "Temperature Rise vs. Ripple Current" plots is the ESR at ambient temperature. The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated. The effects shown herein are based on measured data from a multiple part sample of the parts in question. Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

  The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

   Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.

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